



# DESIGN VALIDATION REPORT

Design and Development Department

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Report Title : KBox A101 Temperature Test Report

**This Validation Report Prepared by KONTRON ASIA PACIFIC DESIGN Sdn Bhd  
for <KEU>**

KONTRON ASIA PACIFIC DESIGN (M) Sdn Bhd

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FORM # : FR00054(1)

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## **REVISION HISTORY**

Rev	Change Number/Description	Date	Change Originator
1.0	Initial Revision	6.5.2014	Shahtishwaren

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## 2 Introduction

### 2.1 Executive Summary

The tested sample fully complies with the requirements set forth in

- IEC 60068-2-1
- IEC 60068-2-2
- IEC 60068-2-14

### 2.2 General, Purpose and objective

This document describes the environmental test procedures, test assembly and device under test (DUT) with the affiliated results and photographs.

### 2.3 Terminology, Definitions and Abbreviations

DUT Device under test  
HDD Hard disk drive  
OS Operating system  
PSU Power supply  
TDP Thermal Design Power

## 3 Performed tests and results

### Test overview

No	Test	Parameters	Start Temp	End Temp	Duration
1	Low Temperature, Operating	Temperature:	-10°C	-10°C	16H
2	High Temperature, Operating	Temperature:	60°C	60°C	16H
3	Change of Temperature, Operating	Temperature:	-10°C	60°C	48H

No	Test	Results	Remark
1	Low Temperature, Operating	PASS	The complete DUT works as designed during and after the test.
2	High Temperature, Operating	PASS	The complete DUT works as designed during and after the test.
3	Change of Temperature, Operating	PASS	The complete DUT works as designed during and after the test.

## 4 Configuration

### 4.1 Test assembly

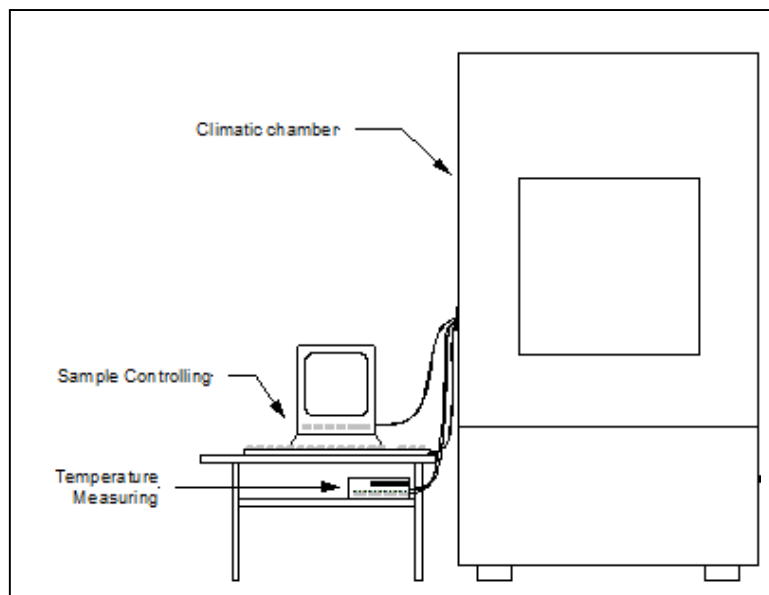


Figure 1: Test assembly

## 4.2 Test measurement equipment

Component	Model	Manufacturer	Ser No	Cal. Date
Climatic chamber	SE-600-10-10	Thermotron	34315	28.4.2015
Measurement module	34970A	Agilent	MY44043308	18.3.2015
20 Channel Multiplexer	34901A	Agilent	MY41026121	18.3.2015
Test software	BurnIn TestV7.1 Pro SIW	Passmark	-	-

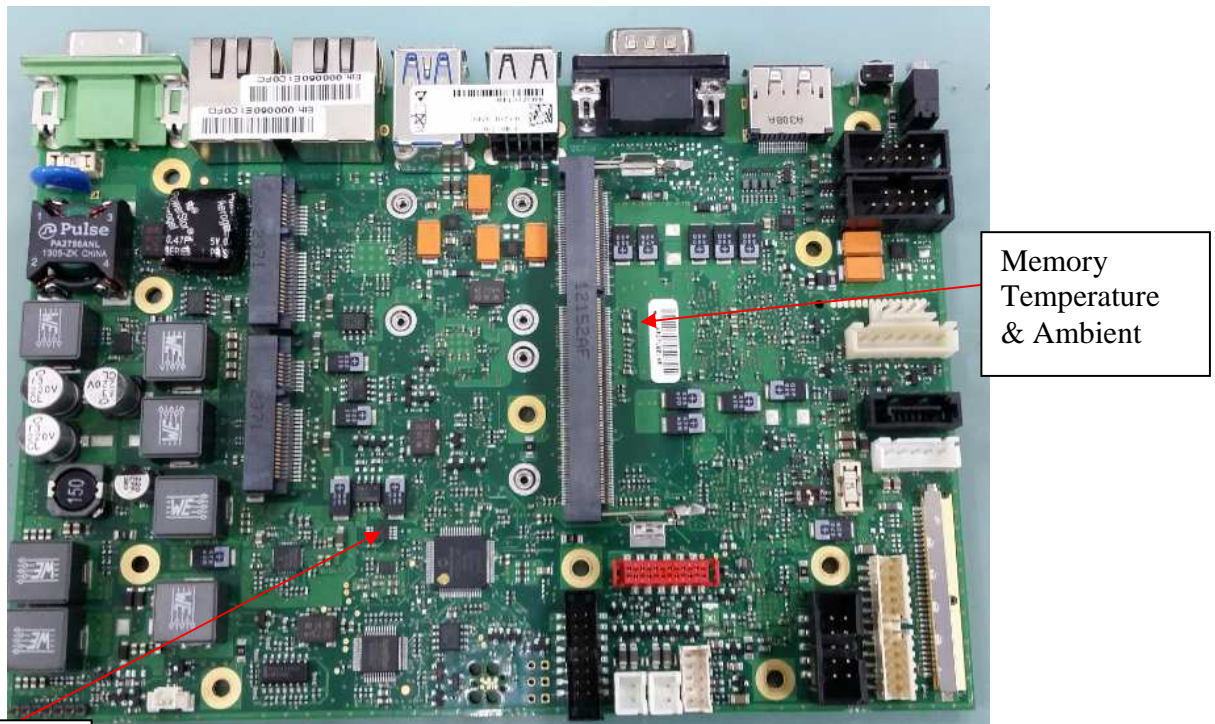
## 4.3 Device under Test

Name	KBox A-101
Part number	2-A0CR-2001
Product Number	483710148
Hardware	CPU: Intel Atom D2550 1.86GHz MB: B749 Memory: 2GB DDR3-SODIMM Ethernet: 10/100/1000 Mbps USB: 4x Cooling: Passive/Fan-less Power: 24V DC IN
Software	Bios: American Megatrends Bios version: 4.6.5.3 OS: Win 7

## Interfaces

Interface	Attached devices
Power In	Power supply, 24V
Display Port	Display via DP cable
USB	Mouse, Keyboard
LAN	LAN cable

## 4.4 Sensor Positions



Sensor IC 1 Ambient Temperature

Figure 2: PCB Top View

Memory Temperature & Ambient

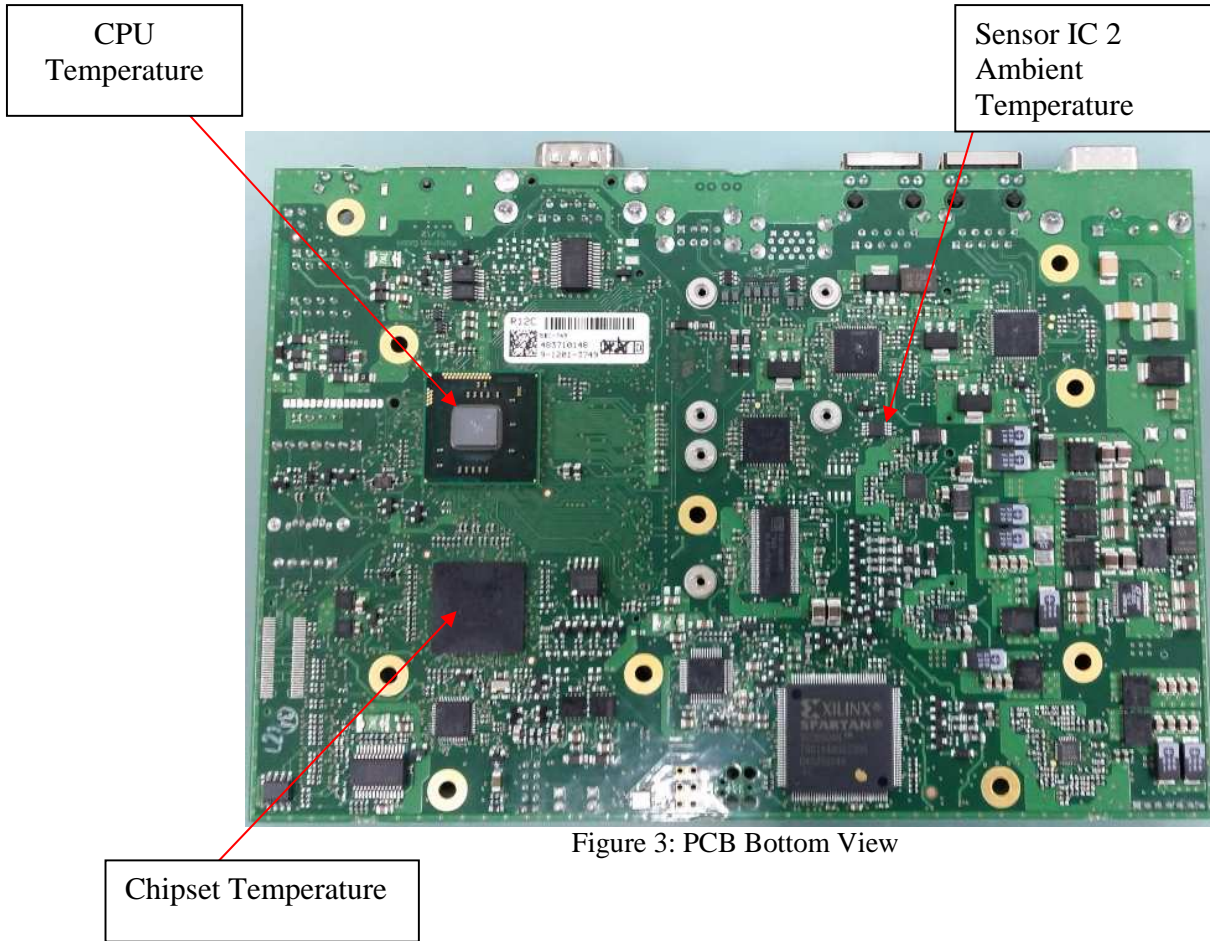


Figure 3: PCB Bottom View

Sensor No	Sensor Position
1	CPU
2	Chipset
3	Memory
4	Memory Ambient Temperature
5	HDD
6	HDD Ambient Temperature
7	Sensor IC 1
8	Sensor IC 2
9	Heat Sink
10	Ambient Temperature Inside DUT
11	Chamber Ambient Temperature
12	Chamber Ambient Temperature

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## 4.5 Test programs

### 4.5.1 BurnIn Test(v.7.1 Pro)

#### Preferences

Menu	Configuration
USB	Max. number of USB ports=4
LAN	Max. number of LAN ports=2
CPU	Intel Atom D2550



#### Tests selected

Test	Configuration
CPU	50%
RAM	50%
2D Graphics	50%
3D Graphics	50%
Ethernet	50%

## 5 Test Procedures and Results

### 5.1 Low Temperature, Operating



#### Pre-test parameter

Parameter	Values ( References)	Results	Status
Checks, measurements	Visual inspection		
	BurnIn Test	 -10DegBIT_log_14042 4_115808.zip	PASS
	SIW	 SIW_FREEMWARE_UUT 3-PC_20140424_1513	PASS



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## Test parameters

Parameter	Values (References)	Status
Conditions	Temperature: -10°C Duration (1cycle): 16h	
Sample status	Operating ( Running BurnIn Test) Position: Vertical	
BurnIn Test Results	 -10DegBIT_log_14042 4_175550.zip	PASS
SIW	 SIW_FREEWARE_UUT 3-PC_20140425_1032	PASS

## Post-test parameter

Parameter	Values ( References)	Results	Status
Checks, measurements	Visual inspection		
	BurnIn Test	 -10DegBIT_log_14042 5_110154.zip	PASS
	SIW	 SIW_FREEWARE_UUT 3-PC_20140428_1031	PASS

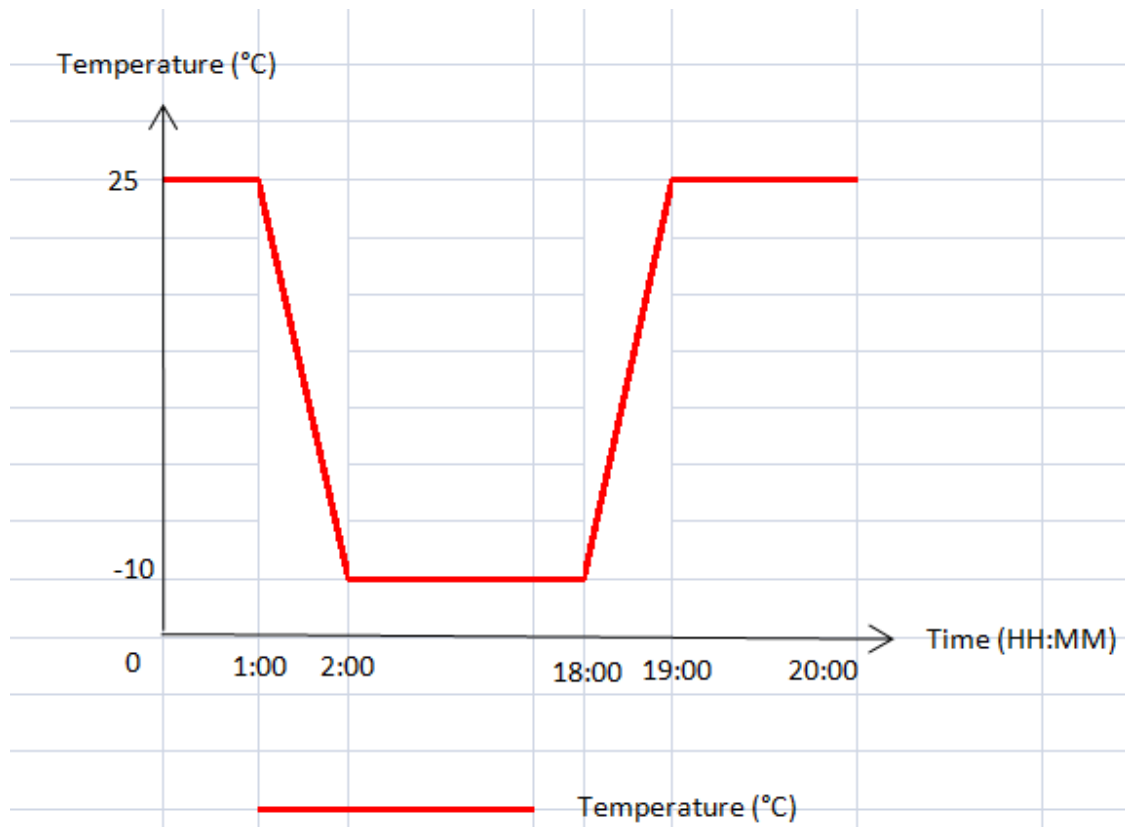


Figure 4: Temperature Diagram, Low temperature, Operating

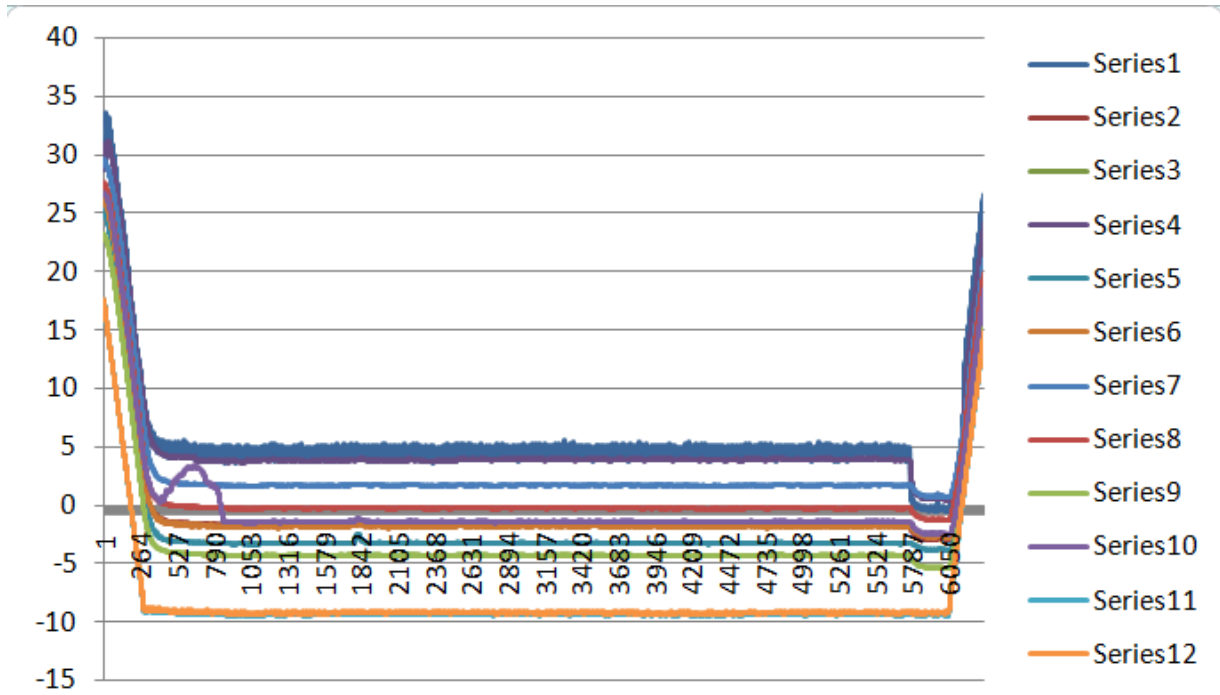






Figure 5: Measurement diagram, Low temperature, Operating

## 5.2 High Temperature, Operating



### Pre-test parameter

Parameter	Values ( References)	Results	Status
Checks, measurements	Visual inspection		
	BurnIn Test	 60DegBIT_log_14042 8_100752.zip	PASS
	SIW	 SIW_FREWARE_UUT 3-PC_20140428_1037.	PASS

## Test parameters

Parameter	Values (References)	Status
Conditions	Temperature: 60°C Duration (1cycle): 16h	
Sample status	Operating ( Running BurnIn Test) Position: Vertical	
BurnIn Test Results	 60DegBIT_log_14042 8_110939.zip	PASS
SIW	 SIW_FREWARE_UUT 3-PC_20140429_1038	PASS

## Post-test parameter

Parameter	Values (References)	Results	Status
Checks, measurements	Visual inspection		
	BurnIn Test	 60DegBIT_log_14042 9_073721.zip	PASS
	SIW	 SIW_FREWARE_UUT3-PC_20140429_103657.zip	PASS

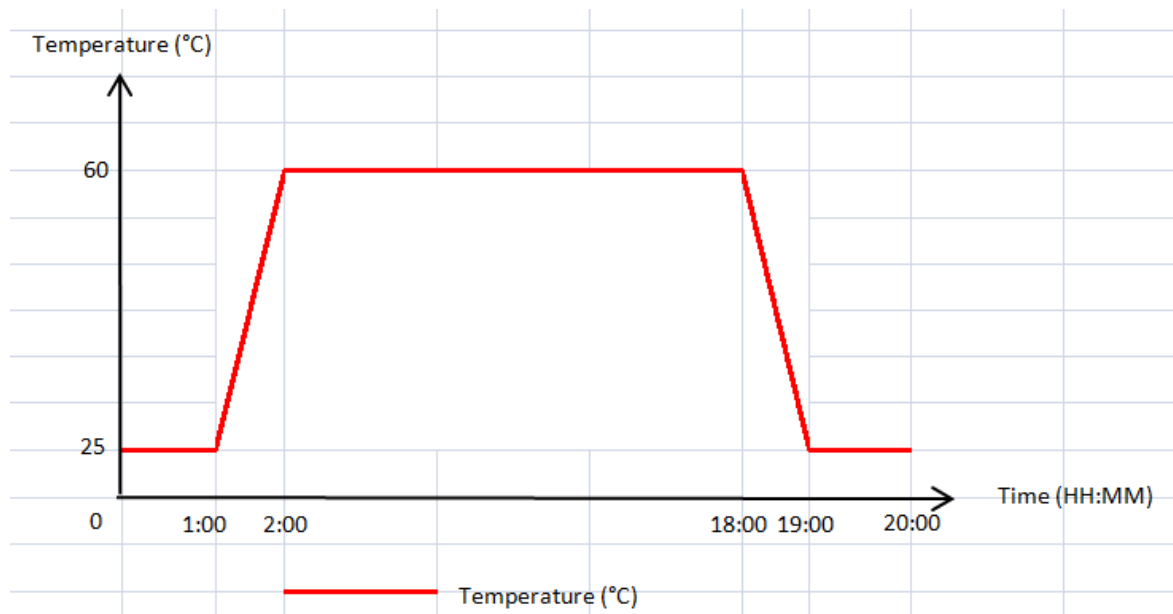


Figure 6: Temperature Diagram, High temperature, Operating

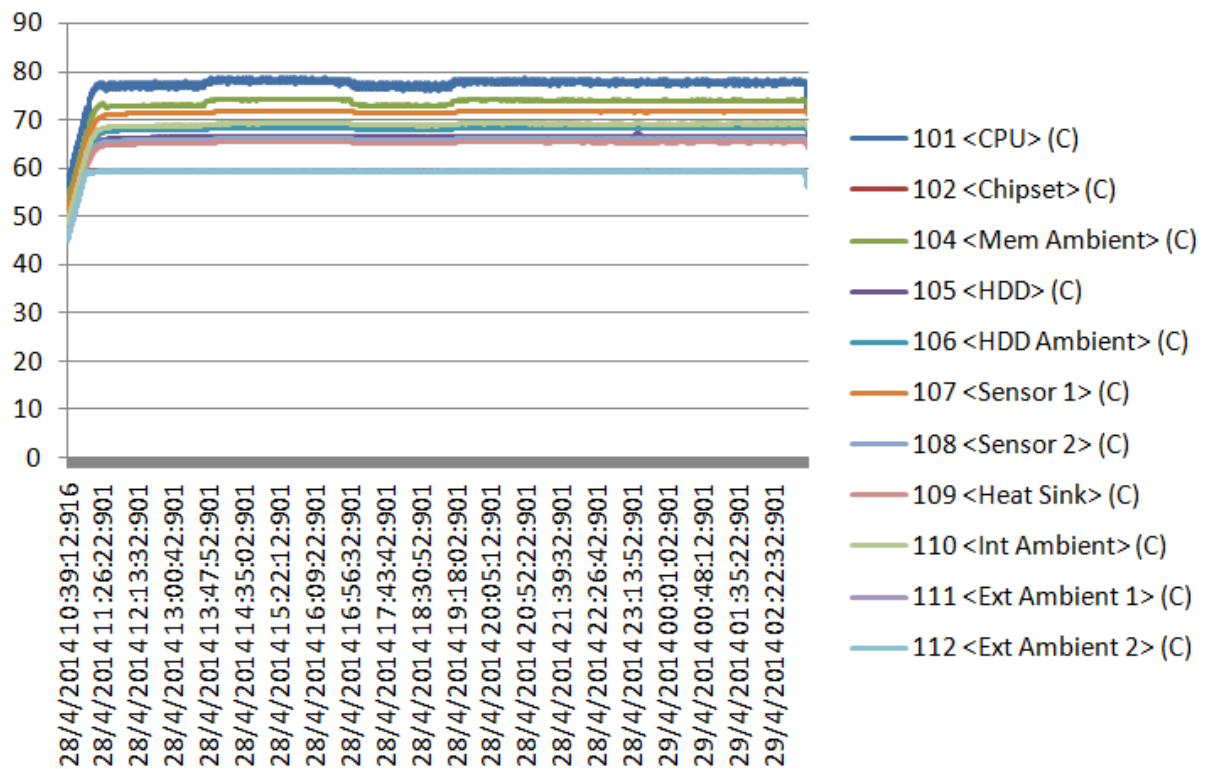




Figure 7: Measurement diagram, High temperature, Operating

Temperature chamber temperature deg C	Sensor No	Sensor Position	Maximum Sensor temperature deg C	Component maximum operating temperature deg C
60	1	CPU	78.7	100
60	2	Chipset	68.9	115
60	3	Memory	76.8	95
60	4	Memory Ambient Temperature	74.3	
60	5	HDD	67.4	70
60	6	HDD Ambient Temperature	68.5	
60	7	Sensor IC 1	71.7	125
60	8	Sensor IC 2	66.1	125
60	9	Heat Sink	65.6	
60	10	Ambient Temperature Inside DUT	69.4	
60	11	Chamber Ambient Temperature	59.6	
60	12	Chamber Ambient Temperature	59.7	



### 5.3 Change of temperature, Operating

#### Pre-test parameter



Parameter	Values ( References)	Results	Status
Checks, measurements	Visual inspection		
	BurnIn Test	 HighLowBIT_log_1404 25_110154_PreTest.zi	PASS

	SIW	 SIW_FREWARE_UUT 3-PC_20140428_1035	PASS
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### Test parameters

Parameter	Values (References)	Status
Conditions	Temperature: -10°C - 60°C Duration (4cycle): 24h	
Sample status	Operating ( Running BurnIn Test) Position: Vertical	
BurnIn Test Results	 HighLowBIT_log_1404 25_172211.zip	PASS
SIW	 SIW_FREWARE_UUT 3-PC_20140426_1036	PASS

### Post-test parameter

Parameter	Values ( References)	Results	Status
Checks, measurements	Visual inspection		
	BurnIn Test	 HighLowBIT_log_1404 28_075200.zip	PASS
	SIW	 SIW_FREWARE_UUT 3-PC_20140428_1034	PASS

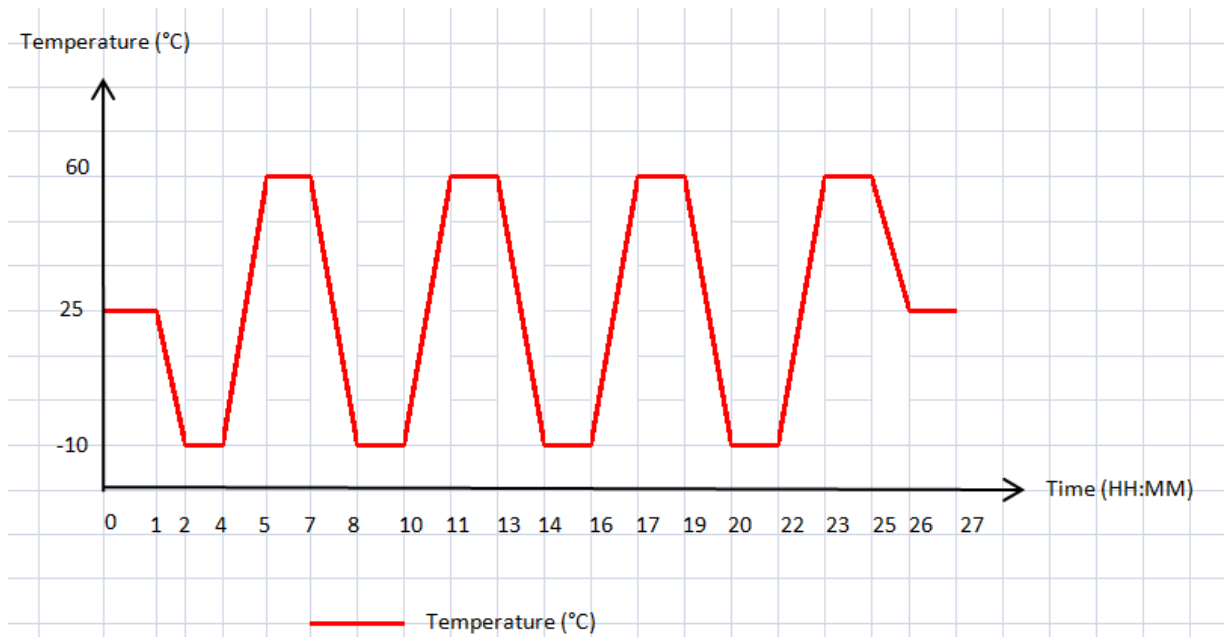


Figure 8: Temperature Diagram, Change of temperature, Operating

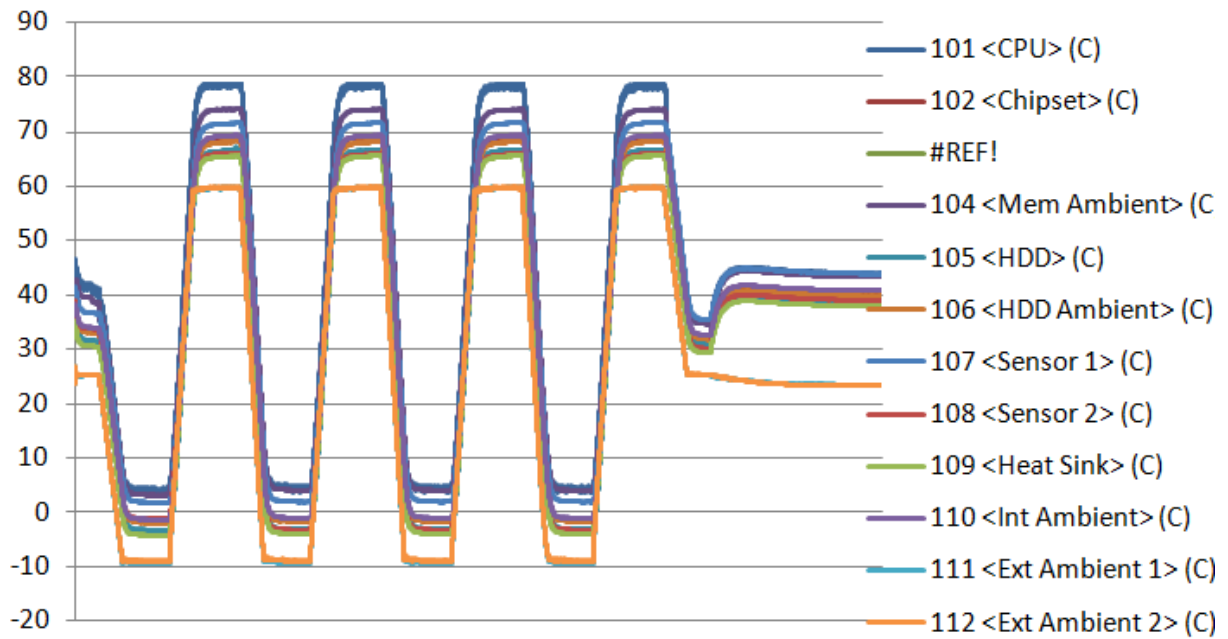


Figure 9: Measurement diagram, Change of temperature, Operating

## 6 Appendix

### 6.1 Photographs



Figure 10: Climatic chamber

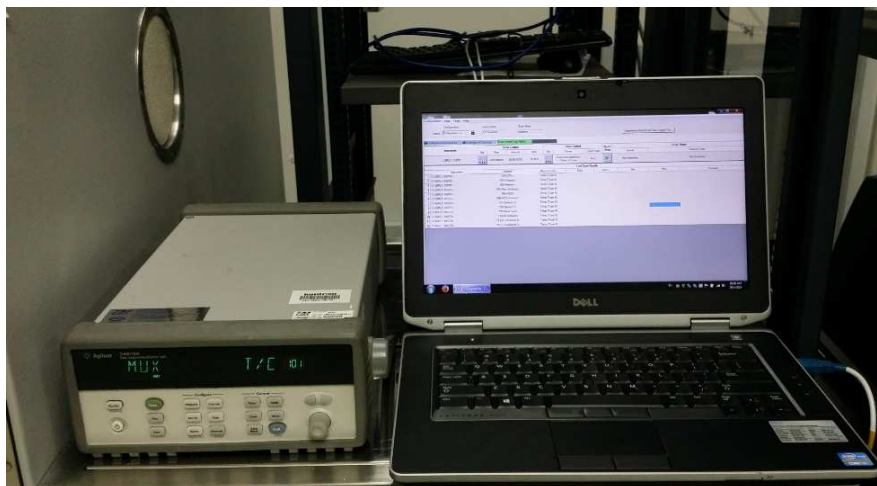


Figure 11: Test assembly (Temp-Data Logger)

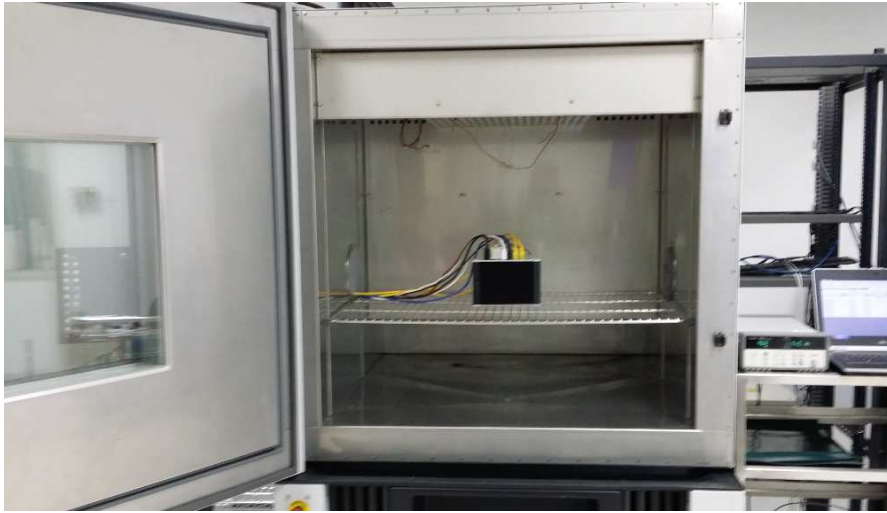


Figure 12: DUT in climatic chamber